

MANUAL DIE BONDER

# T-3002-M

The **T-3002-M** is a manual, precise, high quality die bonder & component placer with superior ergonomic design and a fix die ejector needle. As with all of Tresky's products, the **T-3002-M** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

True Vertical Technology™

Unique pick-up from wafer

Easy to use

MICRO ASSEMBLY

T-3002-M



# TRESKY

Dr. TRESKY AG

Switzerland

Email: [tresky@tresky.com](mailto:tresky@tresky.com)

[www.tresky.com](http://www.tresky.com)

Excellent performance, ergonomically designed and high reliability makes the **T-3002-M** ideal for small and medium production. Typically with a cycle time of approx. 4 sec. (process depending).

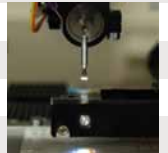
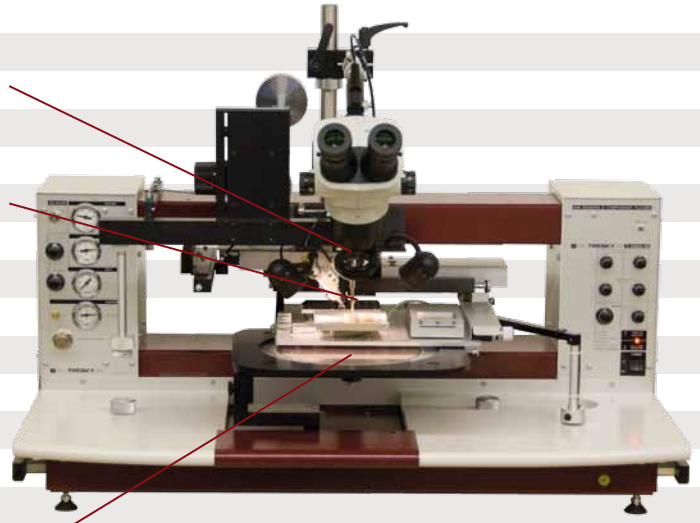
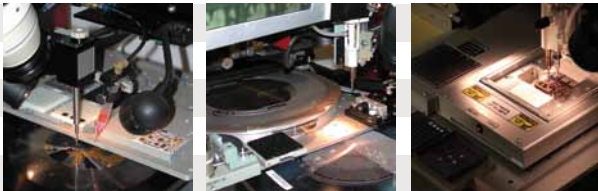
**APPLICATIONS:**

Die Attach, Die Sorting, Flip-Chip, MEMS, MOEMS, VCSEL, Ultrasonic, Thermosonic, RFID, Adhesive Bonding, Eutectic Bonding (AuAu, .....), .....

**FEATURES AND OPTIONS:**

- TRUE VERTICAL TECHNOLOGY™ Z-movement 95mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...
- XY placement stage supporting: Waffle - / Gel - Pack -, Substrate - Holder, various Heating Plates

Some examples of XY placement stage configurations:



- Pick-up from Wafer with Tresky's patented die ejector system, especially suitable for all kind of Si, GaAs and InP dies down to 30µm thickness.

Further Option: Beam Splitter Optics (Flip-Chip09mpaHD)

**TECHNICAL DATA:**

XY- Movement (placement stage):	220mm x 220mm (manual)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (manual)
Spindle Rotation:	360°
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	10µm; 1µm with high accuracy beam splitter (Flip-Chip09mpa)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

**REPRESENTED BY:**

\*\*\*\*\*



**果昱企業股份有限公司**  
**FREESPACIOUS ENTERPRISES CO., LTD.**  
 台灣總公司 TEL: 886-2-2943-9250 FAX: 886-2-2943-9270  
 台中分公司 TEL: 886-4-2560-2282 FAX: 886-4-2560-2282

\*\*\*\*\*

**HEADQUARTERS**

**Dr. TRESKY AG**  
 Boehnirainstr. 13  
 CH-8800 Thalwil  
 Switzerland  
 Tel.: +41 44 772 1941  
 Fax: +41 44 772 1945  
 tresky@tresky.com

**TRESKY Competence Center**  
 Lange Enden 29  
 D-13437 Berlin  
 Germany  
 Tel.: +49 30 683 208 92  
 Fax: +49 30 683 208 94  
 daniel.schultze@tresky.com

**TRESKY Corporation**  
 704 Ginesi Drive, Suite 11A  
 Morganville, NJ 07751  
 USA  
 Tel.: +1 732 536 8600  
 Fax: +1 732 536 0495  
 sales@tresky.com

www.tresky.com

